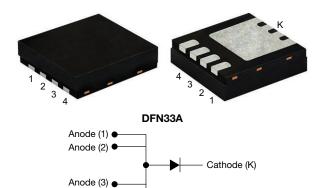


Vishay General Semiconductor

Surface-Mount TMBS[®] (Trench MOS Barrier Schottky) Rectifier



LINKS TO ADDITIONAL RESOURCES

Anode (4) ●



PRIMARY CHARACTERISTICS							
I _{F(AV)}	5 A						
V _{RRM}	60 V						
I _{FSM}	100 A						
V_F at I_F = 2.5 A (T_J = 125 °C)	0.34 V						
T _J max.	150 °C						
Package	DFN33A						
Circuit configuration	Single						

FEATURES

- Low profile package typical height of 0.88 mm
 Available
- Leadless DFN package with side-wettable flanks suitable for customer AOI (Automatic Optical Inspection)



RoHS

COMPLIANT HALOGEN

FREE

- Very low reverse leakage by TMBS Gen3 technology
- Low power losses, high efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
 Automotive ordering code; base P/NHM3
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

For use in low voltage, high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

MECHANICAL DATA

Case: DFN33A

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

MAXIMUM RATINGS ($T_A = 25 \text{ °C}$ unless otherwise noted)							
PARAMETER	SYMBOL	V5N3L63	UNIT				
Device marking code		5L63					
Maximum repetitive peak reverse voltage	V _{RRM}	60	V				
Maximum average forward rectified current (fig. 1)	I _{F(AV)} ⁽¹⁾	5	A				
Maximum average forward rectilied current (lig. 1)	I _{F(AV)} ⁽²⁾	2.7	А				
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	100	А				
Operating junction temperature range	T _J ⁽³⁾	-40 to +150	°C				
Storage temperature range	T _{STG}	-55 to +150	°C				

Notes

(1) With infinite heatsink

⁽²⁾ Free air, mounted on FR4 PCB, 2 oz., standard footprint

 $^{(3)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: dP_D/dT_J < 1/R_{θ JA}

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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)								
PARAMETER	TEST CO	ONDITIONS	SYMBOL	TYP.	MAX.	UNIT		
Instantaneous forward voltage	I _F = 2.5 A	T _J = 25 °C	V _F ⁽¹⁾	0.43	-	v		
	$I_F = 5 A$	1j=25 C		0.49	0.55			
	I _F = 2.5 A	T _J = 125 °C		0.34	-			
	I _F = 5 A			0.43	0.5			
Reverse current	V _B = 60 V	T _J = 25 °C T _J = 125 °C	I _R ⁽²⁾	-	0.1	mA		
Reverse current	$v_{\rm R} = 00 v$	T _J = 125 °C		4	12			
Typical junction capacitance	4.0 V, 1 MH	Ηz	CJ	1050	-	pF		

Notes

⁽¹⁾ Pulse test: 300 µs pulse width, 1 % duty cycle

⁽²⁾ Pulse test: pulse width \leq 5 ms

THERMAL CHARACTERISTICS ($T_A = 25 \text{ °C}$ unless otherwise specified)								
PARAMETER	SYMBOL	TYP.	MAX.	UNIT				
	R _{0JA} (1)(2)	118	148	°C/W				
Thermal resistance	R _{0JA} ⁽³⁾	-	65					
	R _{0JM} ⁽⁴⁾	3.2	4					

Notes

⁽¹⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{BJA}$

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

(3) Thermal resistance junction-to-ambient, free air with device mounted on FR4 PCB, 2 oz., 20 mm x 20 mm pad area

⁽⁴⁾ Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION TABLE

Device code	v	5	N3	L	6	3	н	М3
	1	2	3	4	5	6	7	8
	1	- Vis	hay TME	3S prod	uct			
	2	- Cur	rent rati	ng (5 =	5 A)			
	3	- Pac	kage ty	pe (N3 =	= DFN33	3A)		
	4	- Pro	cess typ	e optior	ר (L = Ioי	w V _F)		
	5	- Vol	tage rati	ng (6 =	60 V)			
	6.	- TM	BS gene	eration o	ption (3	= Gen3)	
	7	- Qua	ality grad	de (H = .	AEC-Q1	01 qual	ified, oth	nerwise =
	8						M3 = ha ead (Pb)	logen-fre -free)

ORDERING INFORMATION (Example)								
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE				
V5N3L63-M3/I	0.031	I	6000	13" diameter plastic tape and reel				
V5N3L63HM3/I (1)	0.031	I	6000	13" diameter plastic tape and reel				

Note

(1) AEC-Q101 qualified

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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

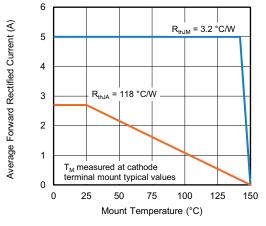


Fig. 1 - Maximum Forward Current Derating Curve

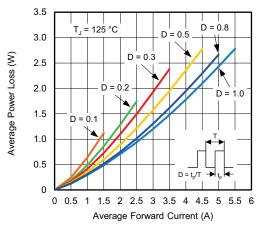


Fig. 2 - Forward Power Loss Characteristics

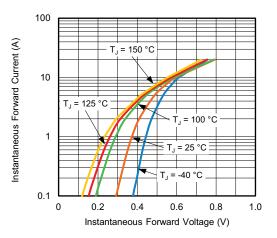


Fig. 3 - Typical Instantaneous Forward Characteristics

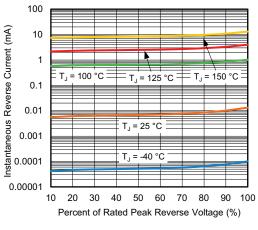


Fig. 4 - Typical Reverse Characteristics

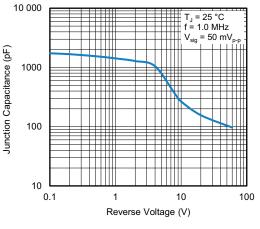


Fig. 5 - Typical Junction Capacitance

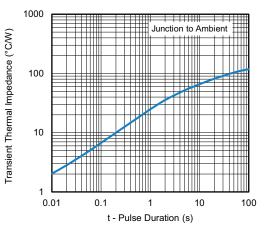


Fig. 6 - Typical Transient Thermal Impedance

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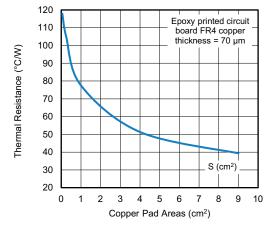


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

Min. 0.005 (0.13) 0.134 (3.40) 0.126 (3.20) 0.039 (0.98) 0.134 (3.40) 0.031 (0.79) 0.126 (3.20) 0.022 (0.55) ref. -Mounting pad layout 0.017 (0.44) 0.011 (0.29) ¥ 0.017 (0.44) 0.094 (2.39) 0.086 (2.19) 0.094 (2.39) 0.030 (0.75) 0.026 (0.65) 0.022 (0.55) 4 0.088 (2.23) - 0.028 (0.70) 0.020 (0.50) 0.028 (0.70) 0.012 (0.30) 0.134 (3.40) 0.088 (2.23) 0.020 (0.50) 0.080 (2.03)

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